



ASE GROUP



日月光半導體 2015第一季法人說明會

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財務長
日月光半導體
2015年4月30日

Safe Harbor Notice



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2014 Annual Report on Form 20-F filed on March 18, 2015.



合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2015	%	Q4 / 2014	%	季變化
營業收入淨額:					
封裝	29,321	45.3%	31,942	41.7%	-8%
測試	6,180	9.6%	6,663	8.7%	-7%
材料直接銷售	861	1.3%	861	1.1%	0%
電子代工服務	28,300	43.8%	37,178	48.5%	-24%
其它	0	0.0%	0	0.0%	
營業收入淨額合計	64,662	100.0%	76,644	100.0%	-16%
營業毛利	12,313	19.0%	16,411	21.4%	-25%
營業淨利 (淨損)	6,292	9.7%	9,846	12.8%	-36%
稅前淨利 (淨損)	5,506	8.5%	9,579	12.5%	-43%
所得稅利益 (費用)	(856)	-1.3%	(1,475)	-1.9%	
非控制權益	(181)	-0.3%	(240)	-0.3%	
歸屬於本公司業主之淨利	4,469	6.9%	7,864	10.3%	-43%
基本每股盈餘 (新台幣元)	0.58		1.02		-43%
稀釋每股盈餘 (新台幣元)	0.56		0.99		-43%
EBITDA	13,470	20.8%	17,257	22.5%	-22%



合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2015	%	Q1 / 2014	%	年變化
營業收入淨額:					
封裝	29,321	45.3%	26,722	48.9%	10%
測試	6,180	9.6%	5,785	10.6%	7%
材料直接銷售	861	1.3%	779	1.4%	11%
電子代工服務	28,300	43.8%	21,365	39.1%	32%
其它	0	0.0%	49	0.1%	
營業收入淨額合計	64,662	100.0%	54,700	100.0%	18%
營業毛利	12,313	19.0%	10,360	18.9%	19%
營業淨利 (淨損)	6,292	9.7%	5,085	9.3%	24%
稅前淨利 (淨損)	5,506	8.5%	4,299	7.9%	28%
所得稅利益 (費用)	(856)	-1.3%	(730)	-1.3%	
非控制權益	(181)	-0.3%	(119)	-0.2%	
歸屬於本公司業主之淨利	4,469	6.9%	3,450	6.3%	30%
基本每股盈餘 (新台幣元)	0.58		0.45		29%
稀釋每股盈餘 (新台幣元)	0.56		0.44		27%
EBITDA	13,470	20.8%	11,378	20.8%	18%



綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2015	%	Q4 / 2014	%	季變化
營業收入淨額:					
封裝	31,546	81.7%	36,359	82.9%	-13%
測試	6,180	16.0%	6,663	15.2%	-7%
材料直接銷售	861	2.2%	862	2.0%	0%
其它	18	0.0%	0	0.0%	
營業收入淨額合計	38,605	100.0%	43,884	100.0%	-12%
營業毛利	9,995	25.9%	13,772	31.4%	-27%
營業淨利 (淨損)	5,546	14.4%	8,931	20.4%	-38%
稅前淨利 (淨損)	5,230	13.5%	9,274	21.1%	-44%
所得稅利益 (費用)	(709)	-1.8%	(1,344)	-3.1%	
非控制權益	(52)	-0.1%	(66)	-0.2%	
歸屬於本公司業主之淨利	4,469	11.6%	7,864	17.9%	-43%
EBITDA	11,937	30.9%	15,801	36.0%	-24%



綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)

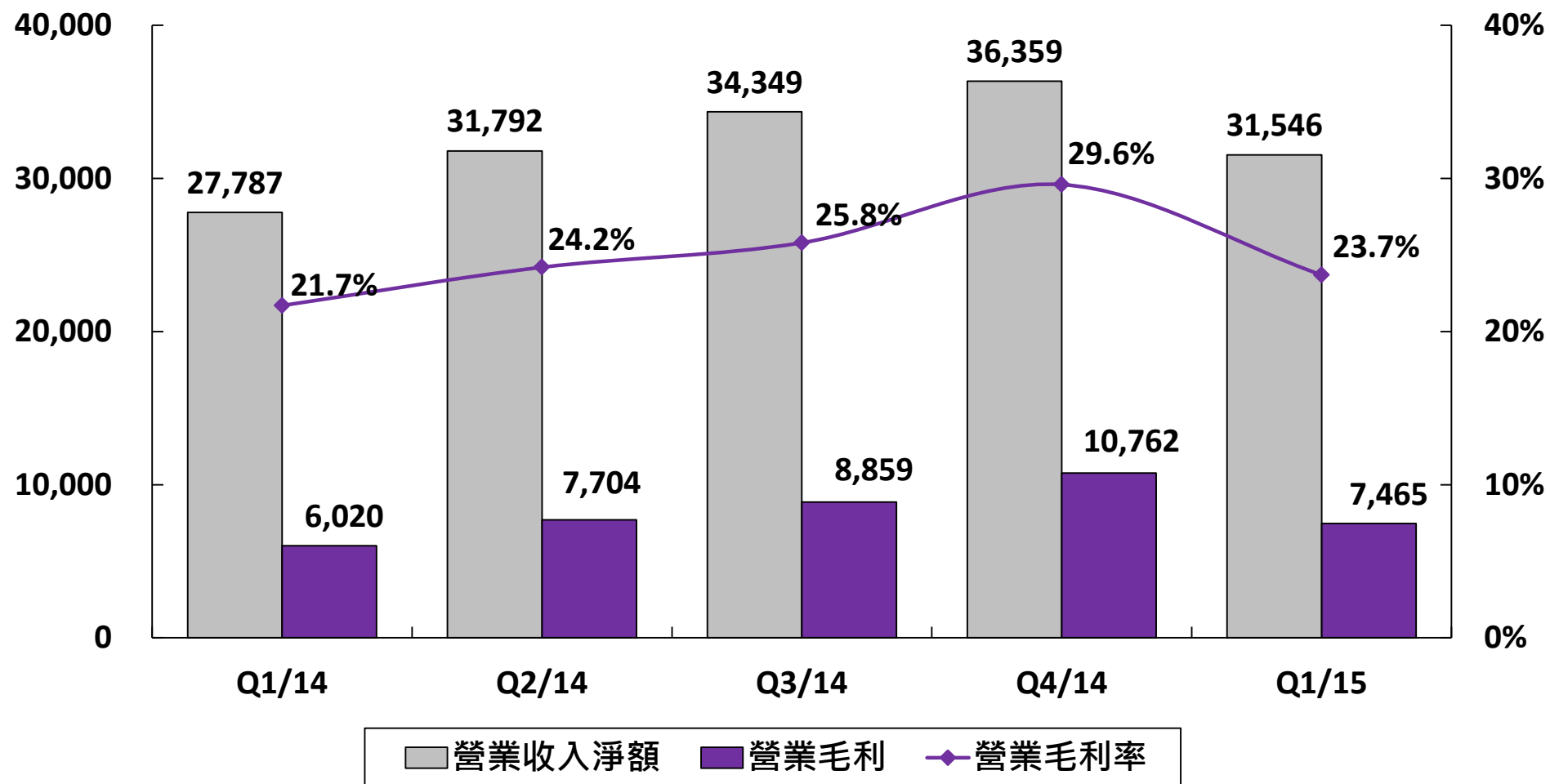


(新台幣百萬元)	Q1 / 2015	%	Q1 / 2014	%	年變化
營業收入淨額:					
封裝	31,546	81.7%	27,787	80.9%	14%
測試	6,180	16.0%	5,785	16.8%	7%
材料直接銷售	861	2.2%	779	2.3%	11%
其它	18	0.0%	0	0.0%	
營業收入淨額合計	38,605	100.0%	34,351	100.0%	12%
營業毛利	9,995	25.9%	8,253	24.0%	21%
營業淨利 (淨損)	5,546	14.4%	4,222	12.3%	31%
稅前淨利 (淨損)	5,230	13.5%	4,053	11.8%	29%
所得稅利益 (費用)	(709)	-1.8%	(573)	-1.7%	
非控制權益	(52)	-0.1%	(30)	-0.1%	
歸屬於本公司業主之淨利	4,469	11.6%	3,450	10.0%	30%
EBITDA	11,937	30.9%	10,160	29.6%	17%



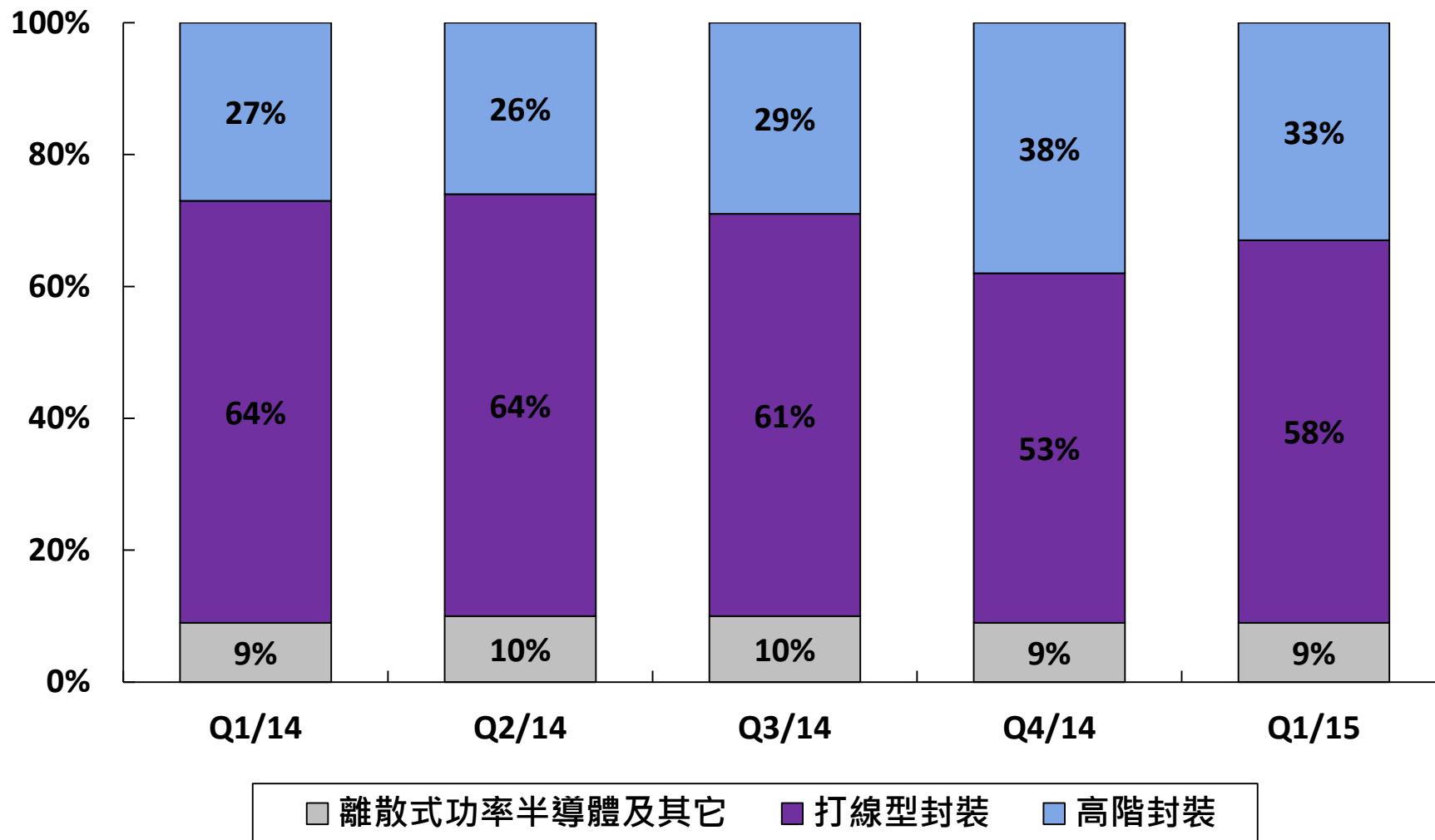
封裝業務

新台幣百萬元



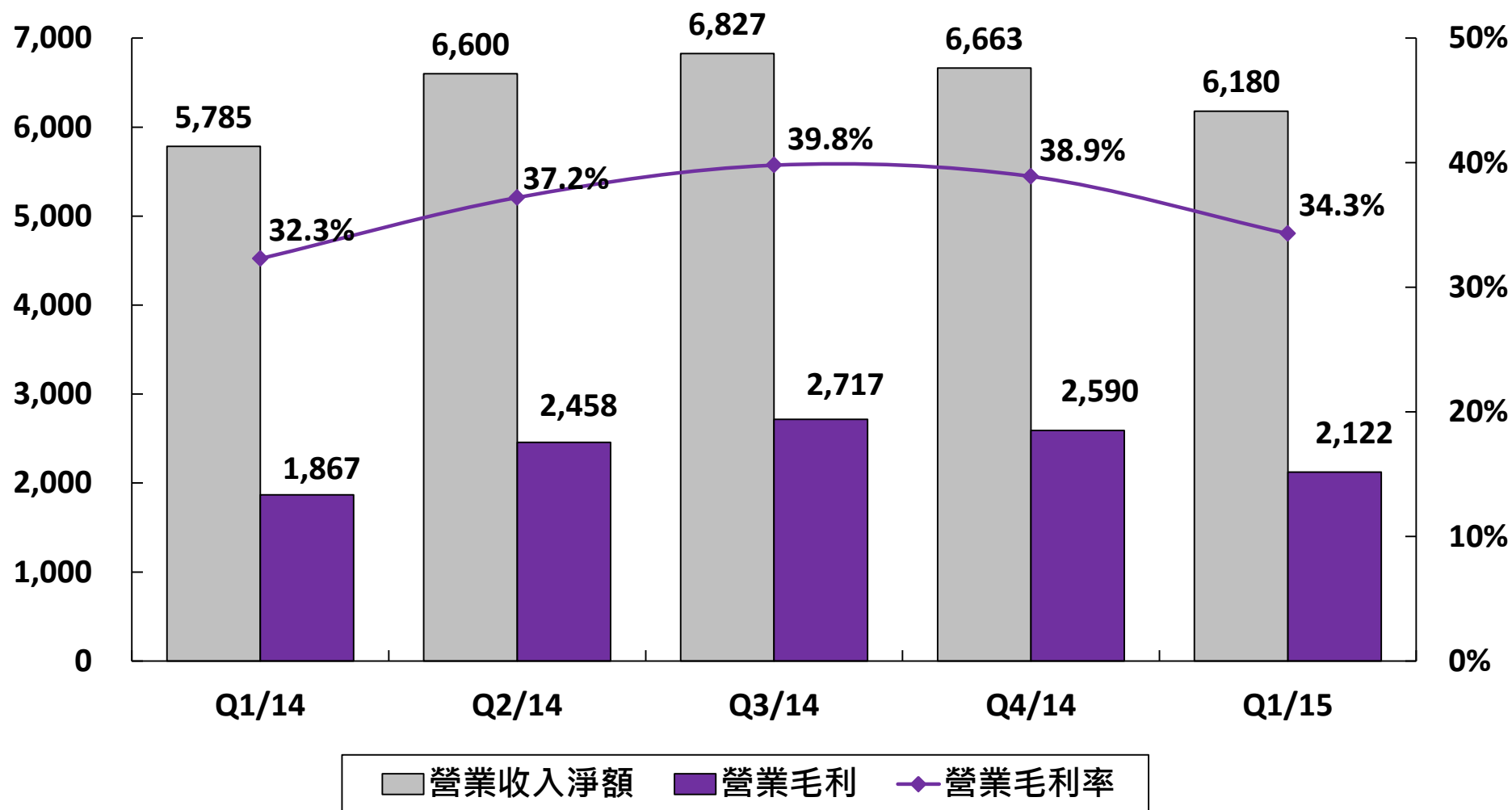
封裝業務

產品組合



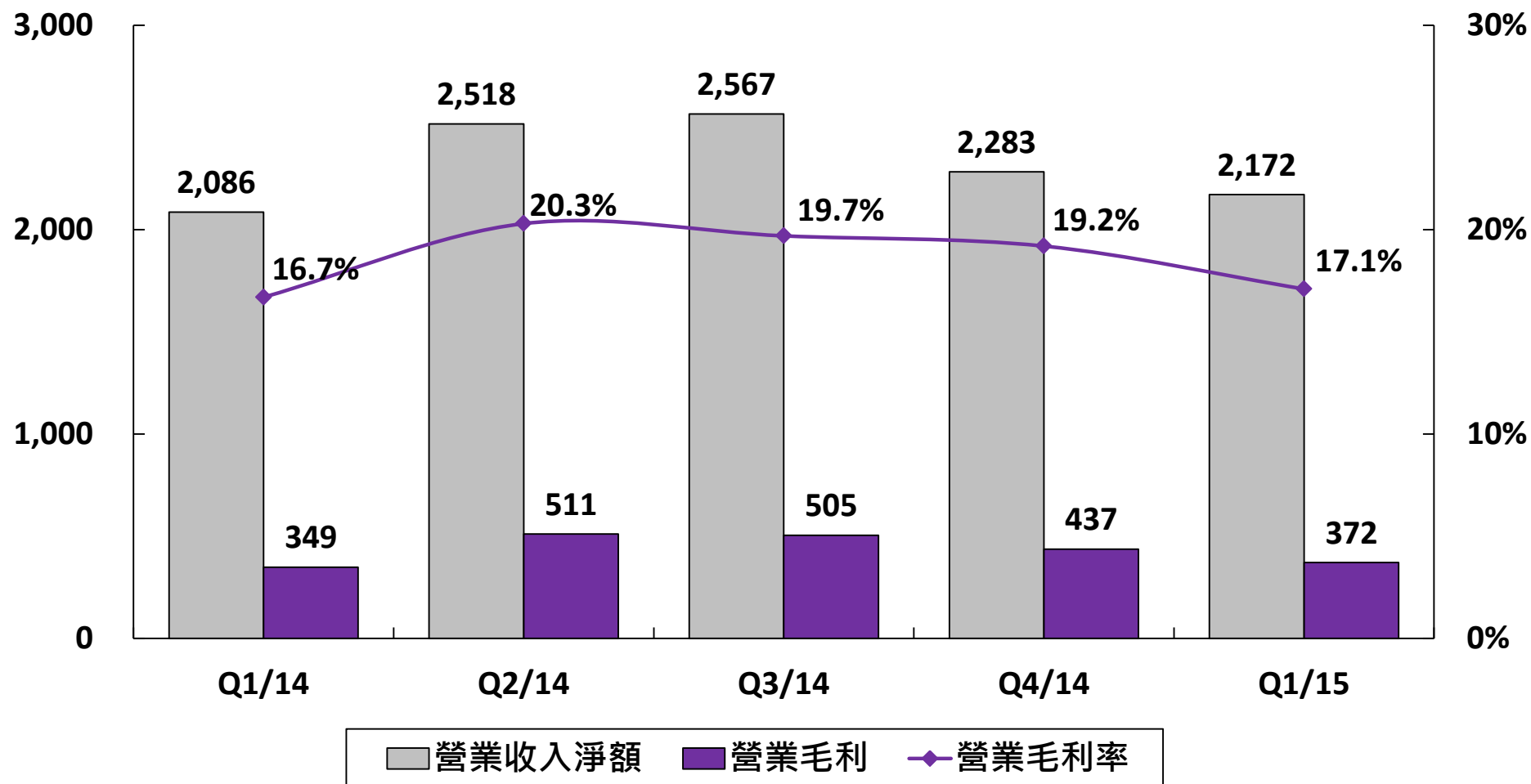
測試業務

新台幣百萬元



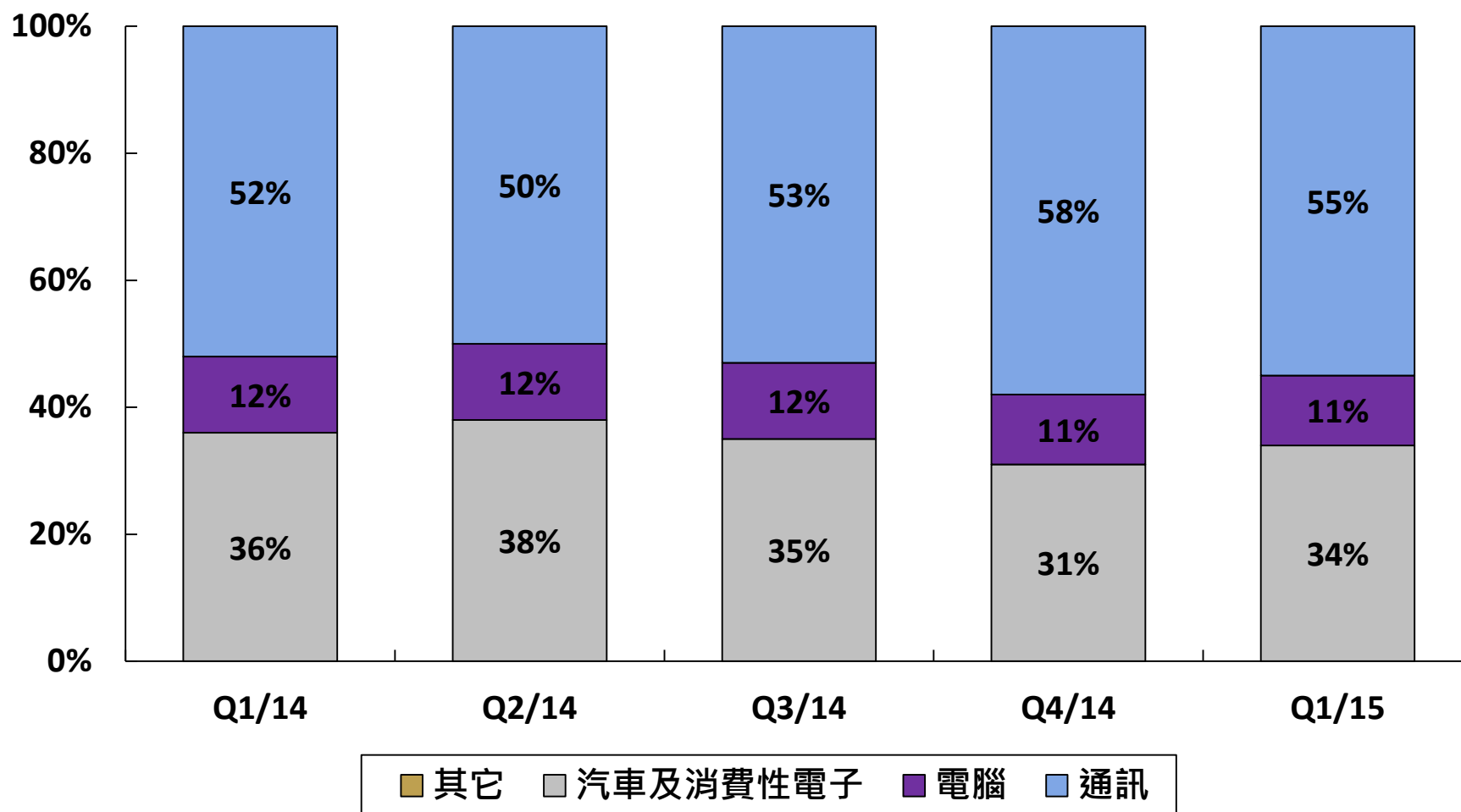
材料業務

新台幣百萬元



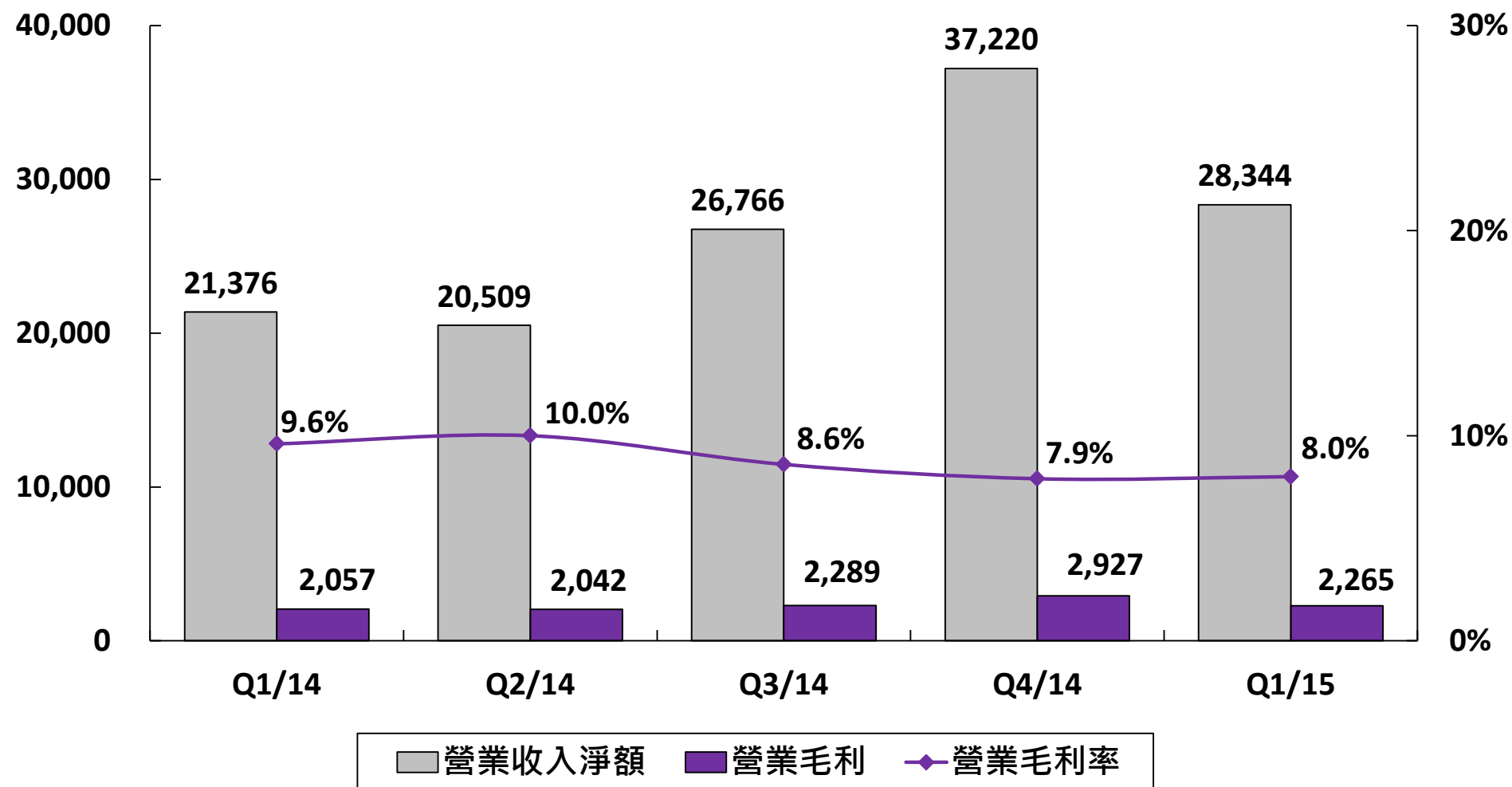
半導體封測營收

產品應用別佔比



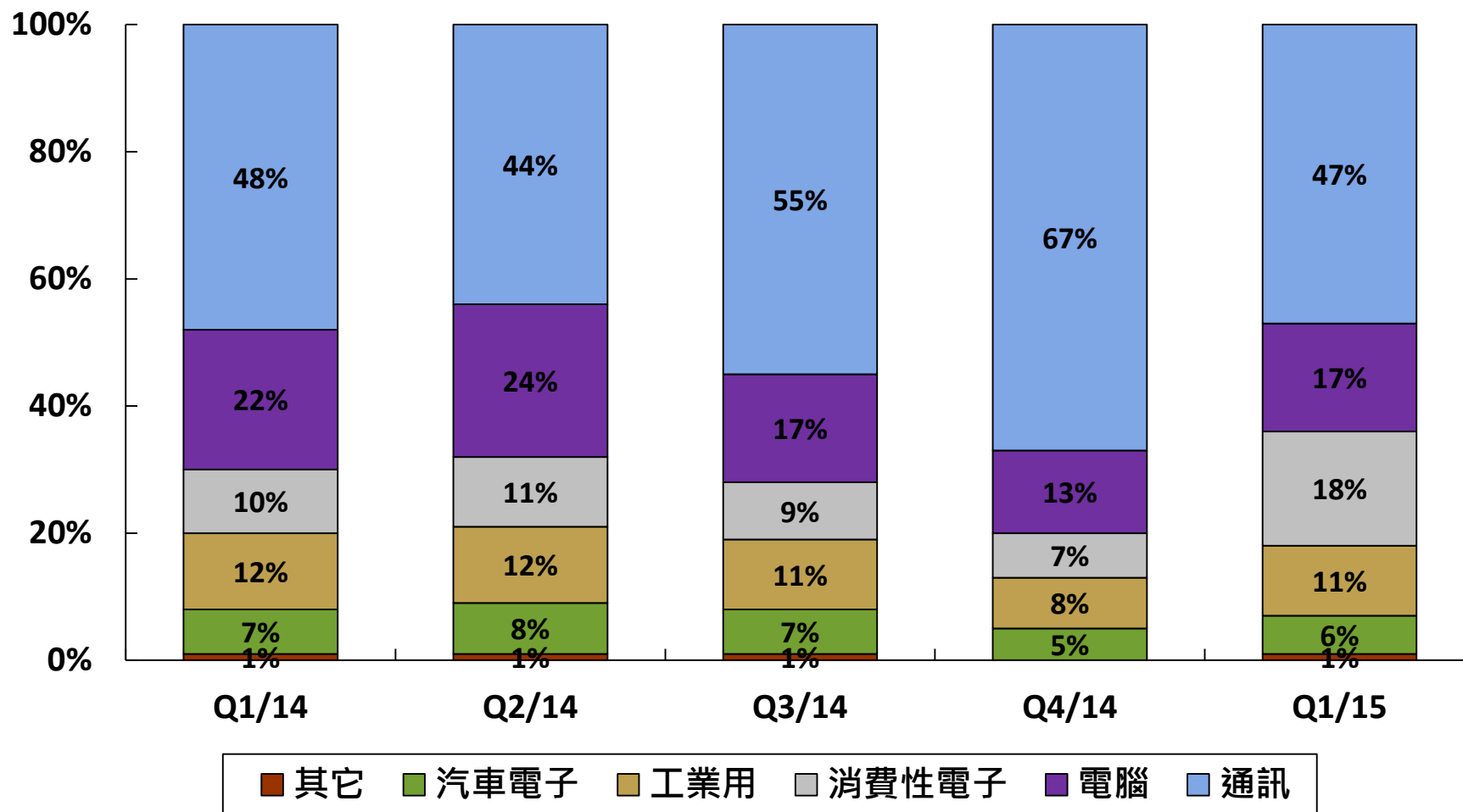
電子代工服務業務

新台幣百萬元



電子代工服務業務

產品應用別



重要資產負債表項目及財務指標

(未經會計師查核)

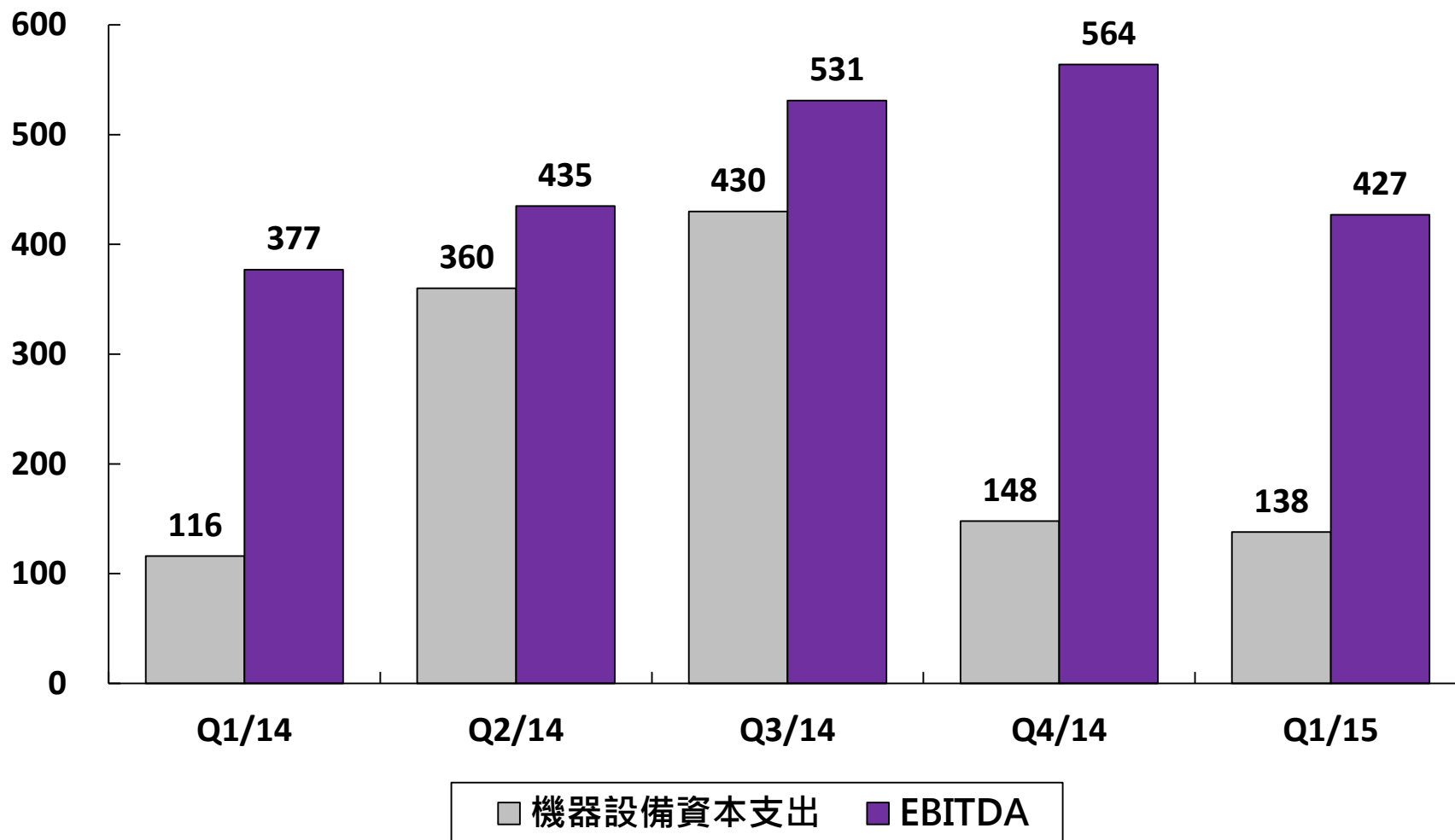


(新台幣百萬元)	2015年3月31日	2014年12月31日	季變化
現金及約當現金	49,414	51,694	-4.4%
金融資產 - 流動	5,510	6,522	-15.5%
金融資產 - 非流動及採用權益法之投資	2,475	2,434	1.7%
不動產、廠房及設備	150,055	151,587	-1.0%
資產總計	322,490	333,985	-3.4%
短期借款	36,661	41,176	-11.0%
一年內到期之長期借款及應付租賃款	1,151	2,835	-59.4%
應付公司債	31,093	31,270	-0.6%
長期借款及應付租賃款	24,751	24,106	2.7%
權益總計 (含非控制權益)	156,648	158,438	-1.1%
當季 EBITDA	13,470	17,257	-21.9%
流動比率	1.48	1.44	
負債權益比率	0.25	0.26	



機器設備資本支出及EBITDA

美金百萬元



2015年第二季業績展望



根據對當前業務狀況的評估及匯率的假設，日月光公司2015年第二季的業績展望如下：

- 半導體封測事業之整體產能應能成長2%，產能利用率則增加0-2%；
- 半導體封測事業之毛利率則與上一季相近；
- 電子代工服務生意量將接近過去兩季之中間值；
- 電子代工服務毛利率因顧客產品供應鏈問題，將較前季經正常化後之毛利率小幅下滑。



Thank You

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